

# Parameter extraction and enhanced scaling laws for advanced SiGe HBTs with HICUM Level 2

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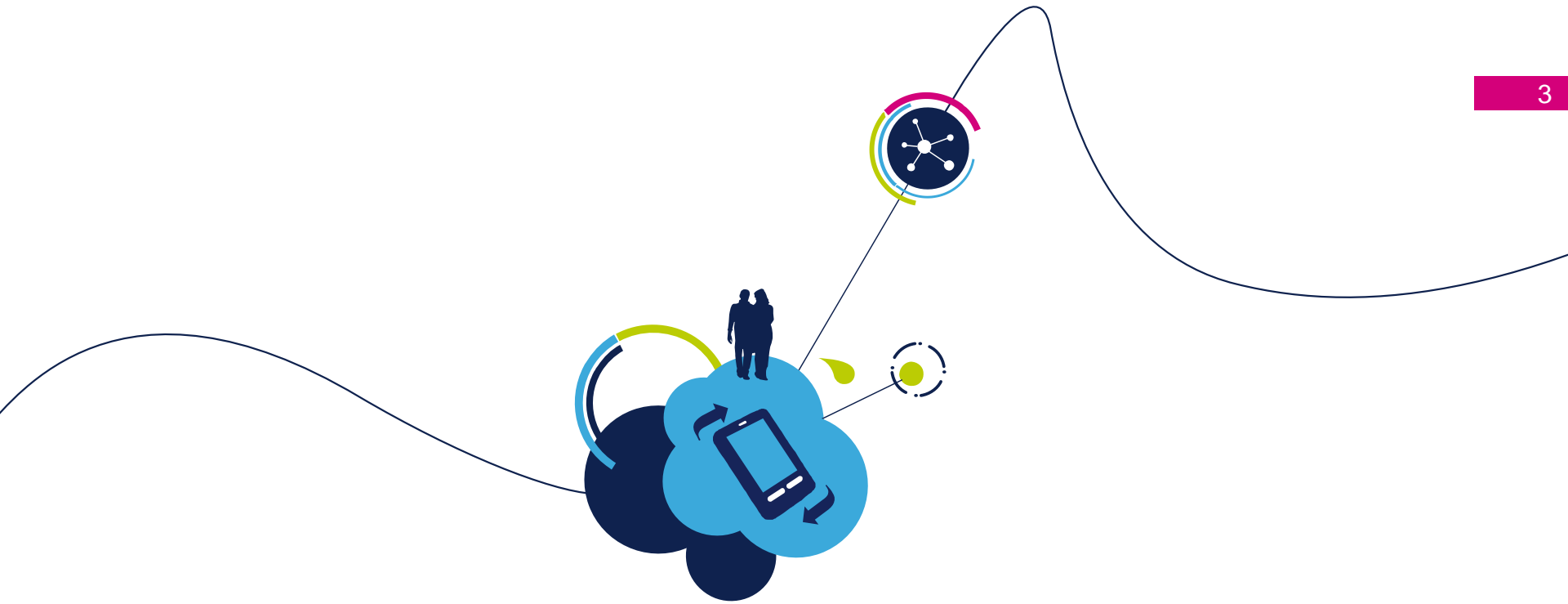
**Modeling of Systems AK**  
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- Introduction & Motivation
- HICUM L2 overview
- Geometry scaling for HBTs
  - Standard scaling approach (P/A)
  - Transfer current scaling –  $\gamma_C$  approach
  - Modeling the bias dependence of  $\gamma_C$
- Example extraction for advanced SiGe HBTs
  - Generic scaling method
  - Transit time scaling
  - Scaling of the internal collector resistance
- Results and Conclusion



# Introduction

- **Circuit design**
  - **Relies on accurately modeled characteristics**
    - **DC behavior** (I/V curves, e.g. collector & base current for a HBT)
      - Affected by self-heating, external resistances
    - **AC behavior** (small signal parameters vs. frequency)
      - Affected by self-heating, external resistances & capacitances  
non quasi-static effects
  - **Various kinds of circuits**
    - Focus on certain transistor characteristics
      - e.g. mixers, power amplifiers at VHF require accurate S-parameter modeling
    - ⇒ Modeling engineer needs to account for all eventualities
- **Process engineering**
  - **Focuses on achieving performance targets**
    - Targets are hard to achieve
    - ⇒ Recent architectures are getting more complex
    - ⇒ Modeling complexity increases

# HICUM L2 2.33 overview [1]

- Physics based compact model for BJTs/HBTs
  - Targets high frequency applications and high currents
  - Has been applied successfully to silicon- and III/V material-based HBTs
  - Standard model available for most commercial simulators

- Large signal equivalent circuit

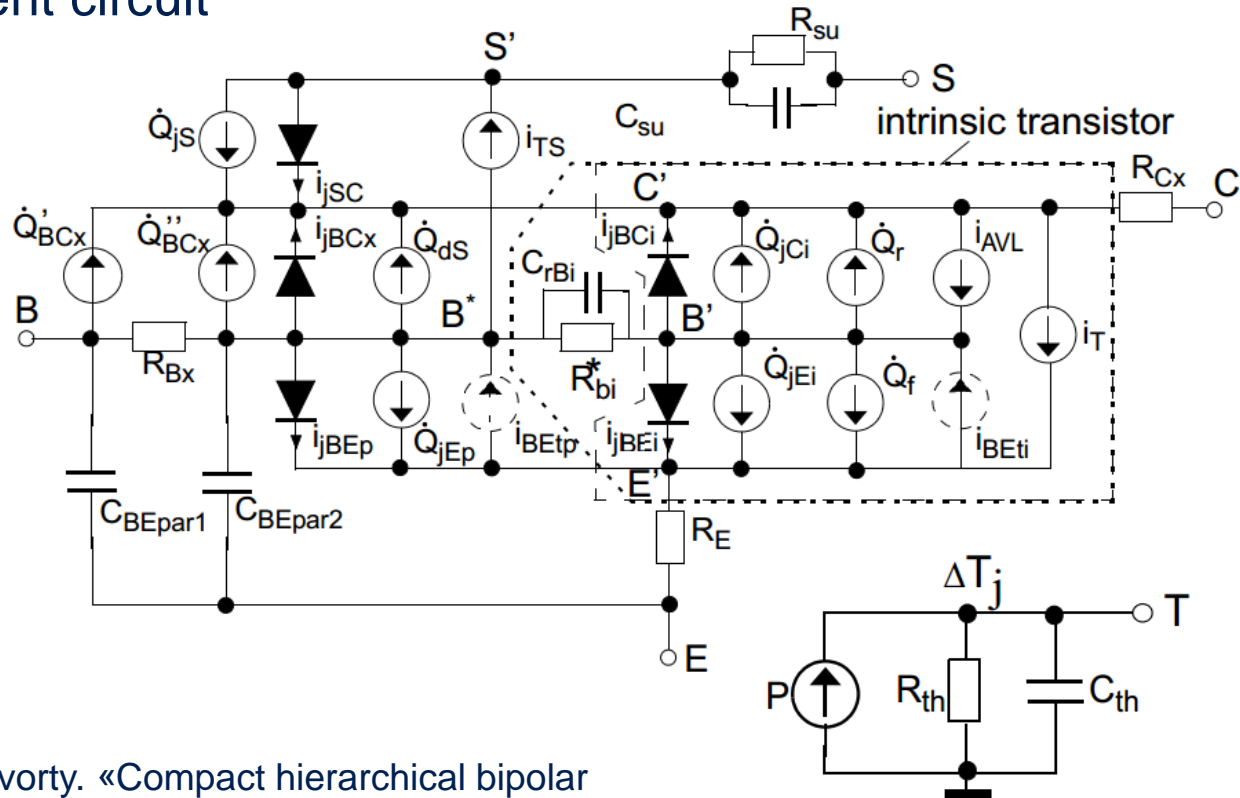
- Internal transistor

- Depletion charges
    - Transfer current
    - Int. base current
    - Int. base resistance
    - Transit-time charge
    - Avalanche

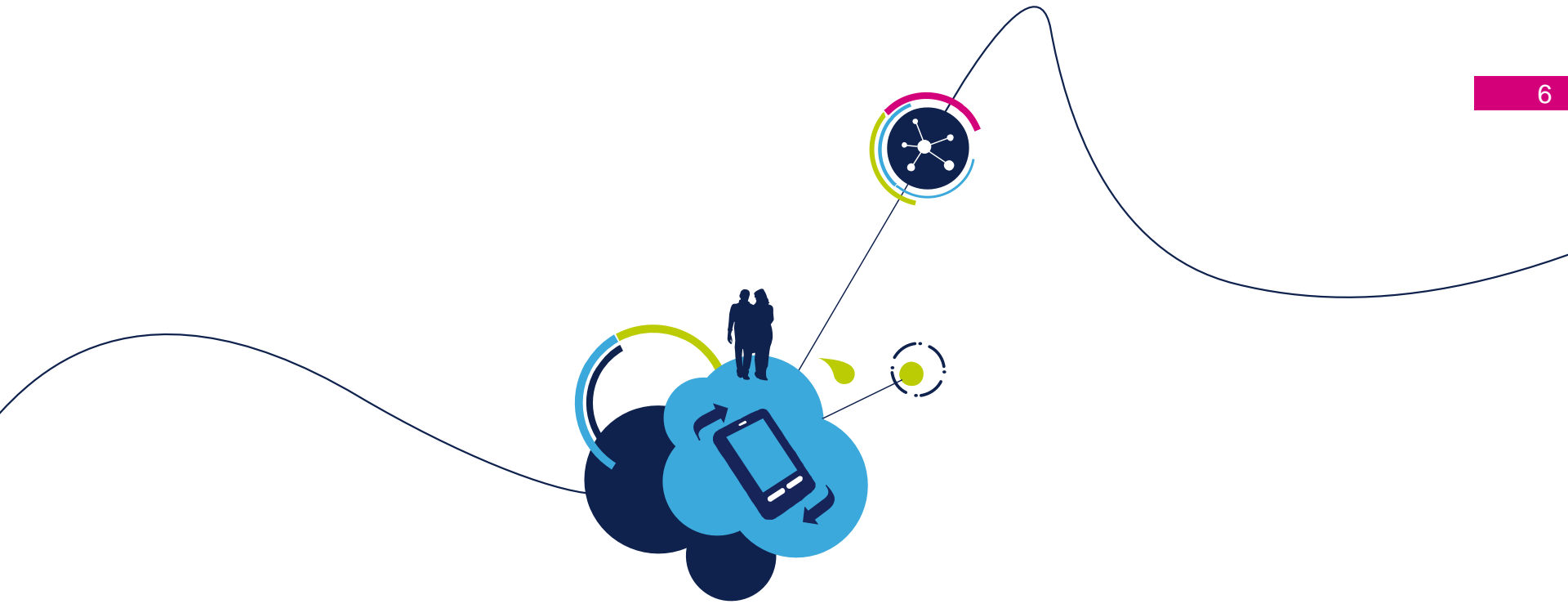
- External elements

- Ext. resistances
    - Ext. base current
    - Ext. capacitances
    - Substrate network
    - Substrate transistor

- Thermal network



[1] M. Schroter, A Chakravorty. «Compact hierarchical bipolar transistor modeling with HICUM». World Scientific, 2010.

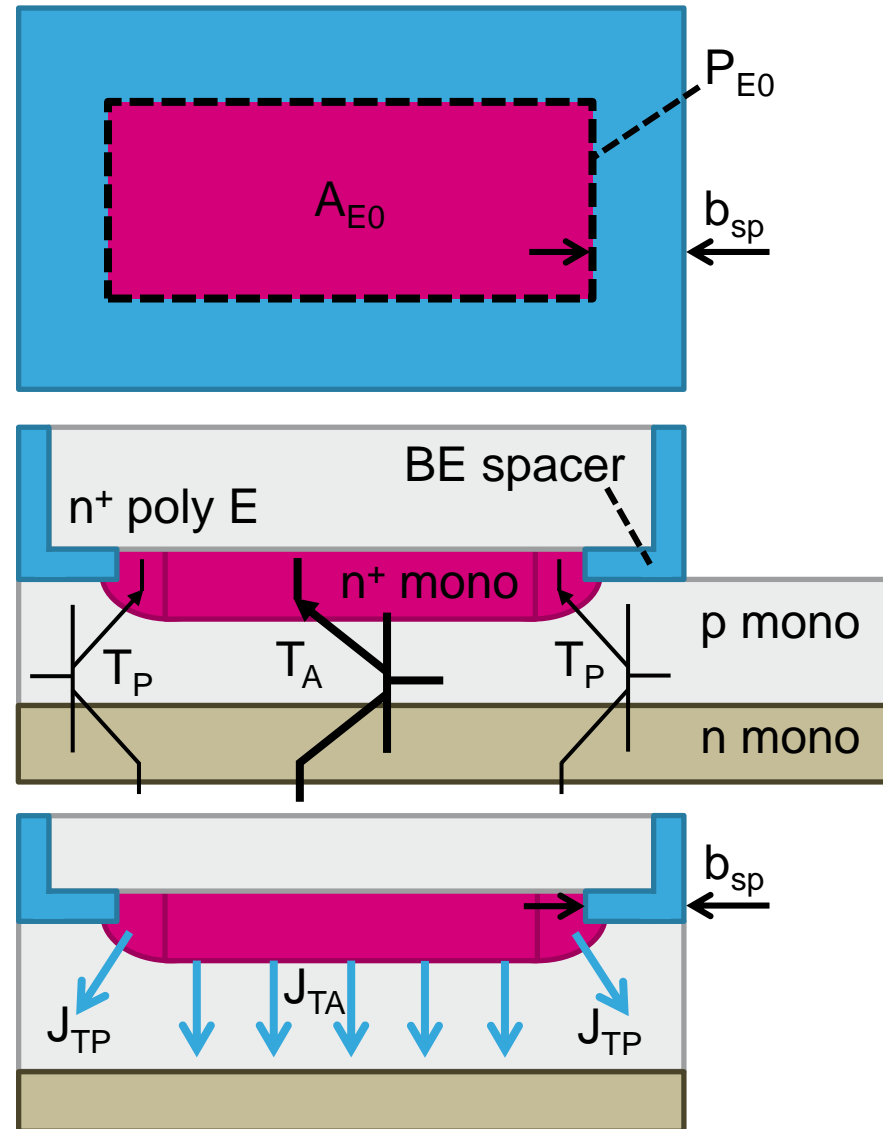


# Geometry scaling for HBTs

# Geometry scaling for HBTs

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- Circuit design
  - Requires different transistor sizes for different types of applications
  - ⇒ Necessary to perform geometry scaling
- Geometry conventions – top view
  - Blue area
    - Corresponds to drawn emitter area
  - Red area
    - Emitter area enclosed by BE-spacer
- Cross-section of typical HBT
  - Consists of two transistors
    - Transistor associated with area ( $A_{E0}$ )
    - Transistor associated with perimeter ( $P_{E0}$ )
  - Total transfer current
$$I_{T,tot} = J_{TA}A_{E0} + J_{TP}P_{E0}$$



# Standard scaling approach (P/A)

- Example for base collector capacitance

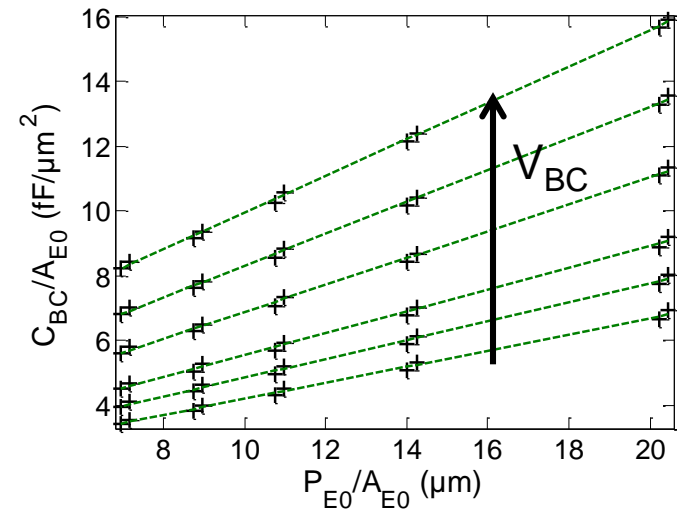
- Measure capacitance for various transistor widths and lengths

$$C_{BC,meas} = C_{jCi}A_{E0} + C_{jCx}P_{E0}$$

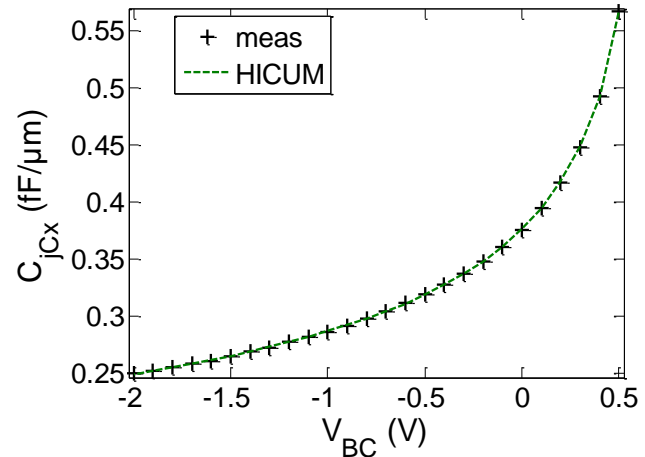
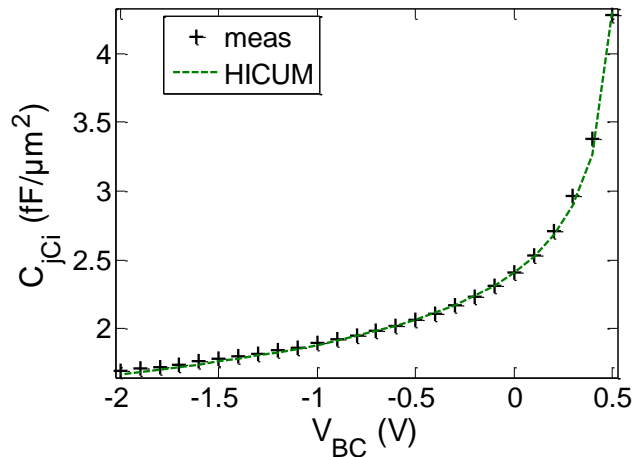
- Normalize on area

$$C_{BC,meas}/A_{E0} = C_{jCi} + C_{jCx}P_{E0}/A_{E0}$$

- ⇒ Offset corresponds to area component  
Slope corresponds to perimeter



- Result (measurement data B55 [2])



[2] P. Chevalier et al. « A 55 nm Triple Gate Oxide 9 Metal Layers SiGe BiCMOS Technology Featuring 320 GHz  $f_T$  / 370 GHz  $f_{MAX}$  HBT and High-Q Millimeter-Wave Passives ». Proc. IEEE IEDM, 2014.



# Transfer current scaling - $\gamma_C$

- HICUM model description

- Consists of various elements for perimeter and area
  - Capacitances, base current
- Does not feature peripheral transfer current due to various reasons
  - Was not necessary up to now, as  $\gamma_C$  approach worked reasonably well (P & A components behaved similarly)
  - Would increase simulation runtime and extraction effort

- The  $\gamma_C$  approach – example on TCAD data

- Associate perimeter contribution to effective area

$$I_{T,tot} = J_{TA}A_{E0} + J_{TP}P_{E0}$$

$$I_{T,tot} = J_{TA}(A_{E0} + J_{TP}/J_{TA}P_{E0})$$

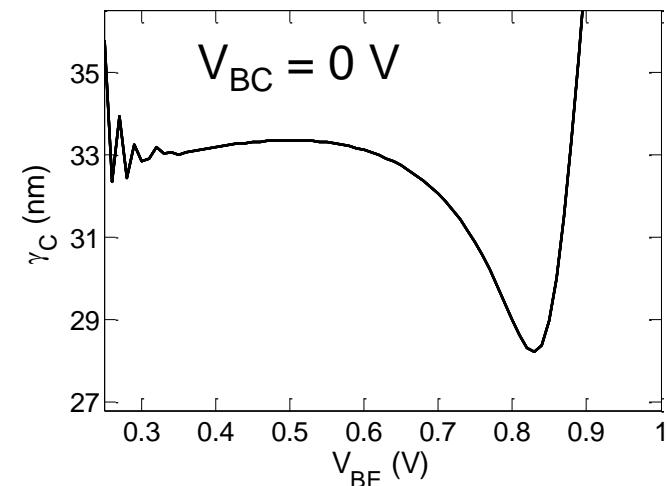
$$A_{E,eff} = A_{E0} + \gamma_C P_{E0}$$

$$\gamma_C = J_{TP}/J_{TA}$$

- Perform standard P/A scaling and calculate  $\gamma_C$

- Usual characteristics of  $\gamma_C$

- Bias independent up to medium current range
  - For high injection, self-heating and external resistances vary for different transistor sizes  
=> will cover variable  $\gamma_C$



# $\gamma_C$ approach - consistency with capacitances

- Simplified transfer current description

- Weight factor  $h_{jEi}$  describes low current behavior

$$I_{T,tot} = \frac{c_{10} \exp(V_{BEi}/V_T)}{Q_{p0} + h_{jEi} Q_{jEi}}$$

- Scaling of transfer current vs. capacitances

- Transfer current is scaled with effective emitter area

$$I_{T,tot} = J_{TA} A_{E,eff} \quad \Rightarrow \quad c_{10} = c_{10A} A_{E,eff}^2$$

$$Q_{p0} = Q_{p0A} A_{E,eff}$$

- Capacitances are scaled with actual emitter dimensions (must match AC characteristics)

$$Q_{jEi} = Q_{jEiA} A_{E0}$$

⇒ Will lead to discrepancy for transfer current

- Solution

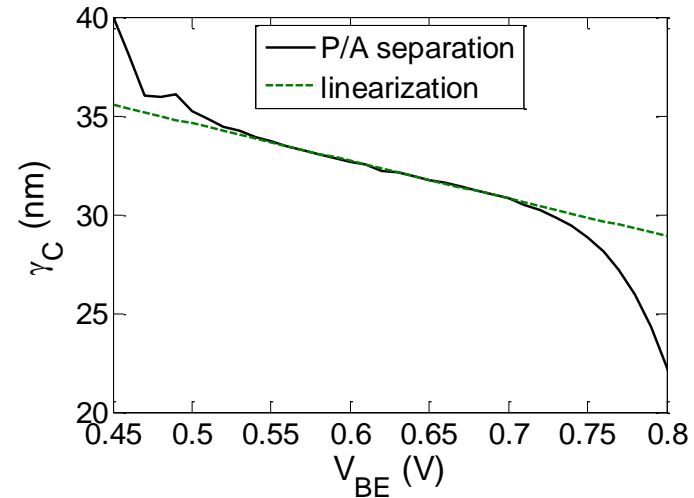
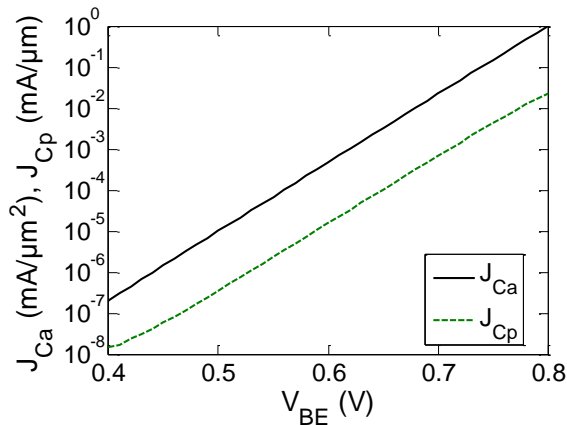
- Adjust weight factor  $h_{jEi}$  to fulfill scaling of  $I_{T,tot}$

$$h_{jEi} = h_{jEiA} \frac{A_{E,eff}}{A_{E0}}$$

$$I_{T,tot} = \frac{c_{10A} A_{E,eff}^2 \exp(V_{BEi}/V_T)}{Q_{p0A} A_{E,eff} + h_{jEiA} \frac{A_{E,eff}}{A_{E0}} Q_{jEiA} A_{E0}} = A_{E,eff} \frac{c_{10A} \exp(V_{BEi}/V_T)}{Q_{p0A} + h_{jEiA} Q_{jEiA}} = J_{TA} A_{E,eff}$$

# $I_T$ for recent technologies

- $\gamma_C$  approach for measurement data (B55)
    - Exhibits linear bias dependence
- => Standard  $\gamma_C$  approach not applicable



## • Possible solution

- Similar behavior observed for process of IHP [3]
  - Method tries to merge different bias dependence of  $J_{TA}$  &  $J_{TP}$  by adjusting weight factor  $h_{jEi}$
- Several prerequisites
  - Similar voltage dependence of  $Q_{jEp}$  &  $Q_{jEi}$
  - Similar voltage dependence of  $h_{jEi}$  &  $h_{jEp}$
  - Several simplifications in equations

$$I_{T,tot} = \frac{c_{10} \exp(V_{BEi}/V_T)}{Q_{p0} + h_{jEi} Q_{jEi}}$$

# Bias dependent $\gamma_C$ [3]

## • Methodology

- Perform standard P/A separation to obtain area and parameter components
- Run extraction for area component
- Run extraction for perimeter component
  - Fix  $Q_{jEp} = Q_{jEi}$  & fix  $a_{hjEi} = a_{hjEp}$   
(identical voltage dependence of  $h_{jEi}$  and  $h_{jEp}$  and charge)

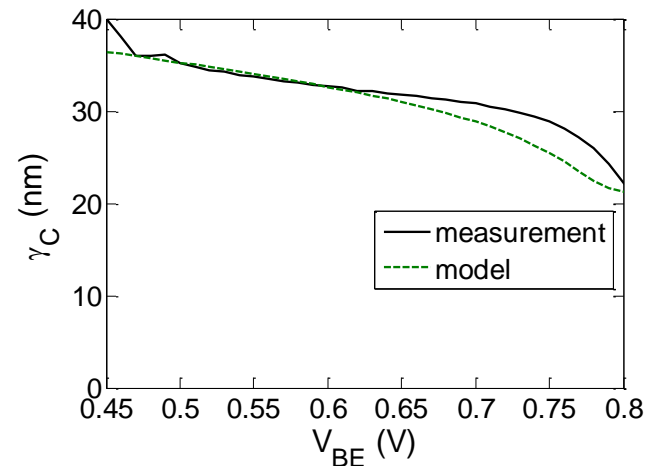
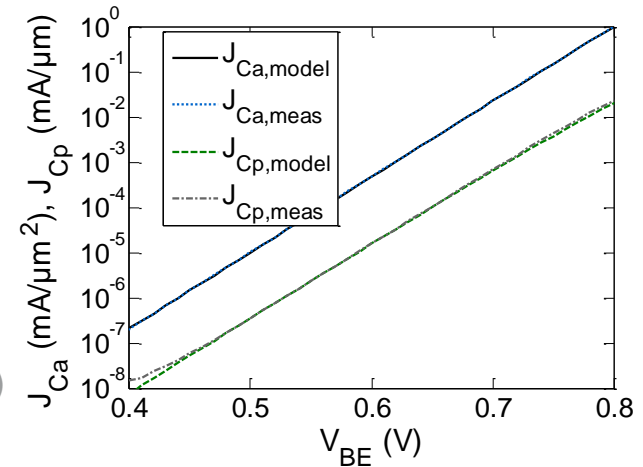
## • Scaling

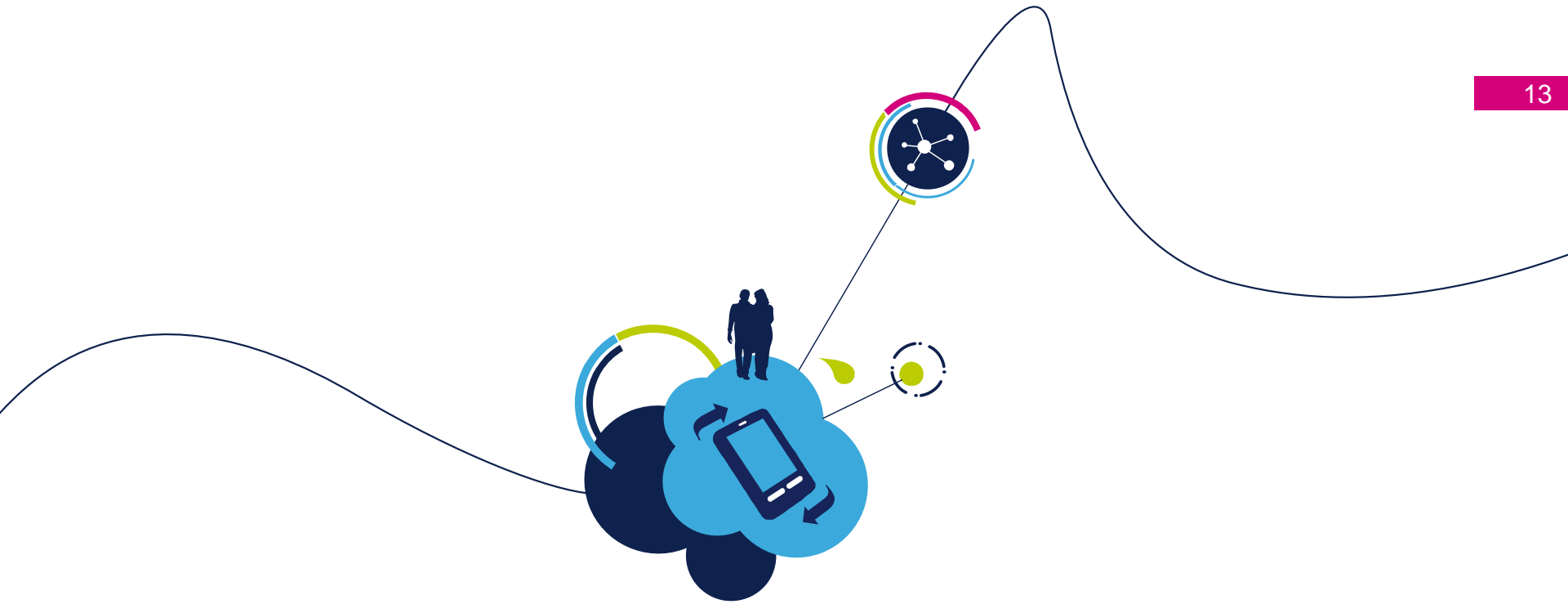
- Effective  $h_{jEi}$ 
  - Courtesy of Didier Céli
  - Identical result to [3], but HICUM L2 description

$$h_{jEi,eff} = h_{jEi} \frac{1 + \gamma_{C0} \frac{h_{jEp}}{h_{jEi} A} \frac{P_{E0}}{A_{E0}}}{1 + \gamma_{C0} \frac{P_{E0}}{A_{E0}}}$$

## • Verification

- Run simulations for all transistors considered in extraction
- Perform P/A separation on synthetic data
- Compare  $\gamma_C$





# Example extraction for B55

(focusing on selected characteristics)

# A generic scaling approach

- Methodology

- Run single transistor extraction for available geometries
- Check geometry dependence of extracted parameters

- Bias dependent  $h_{jEi}$  and  $a_{hjEi}$

- Weight factor  $h_{jEi}$

- Dotted line (blue): approach of [3]
- Dashed line (green): model of [3] applied to single transistor extraction data

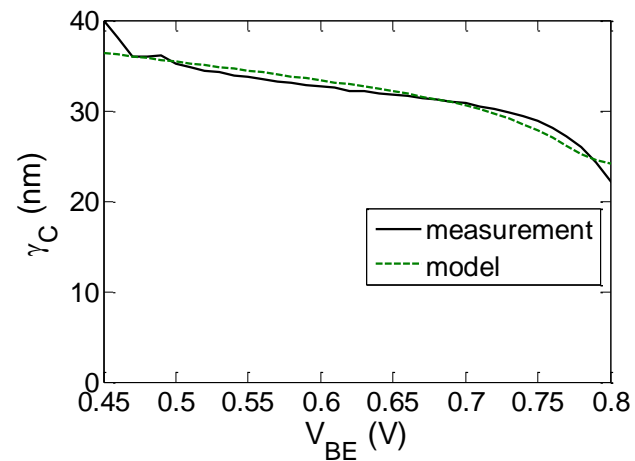
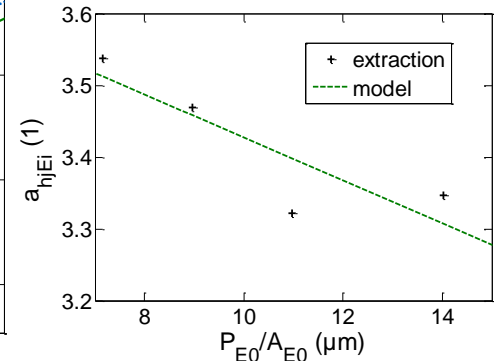
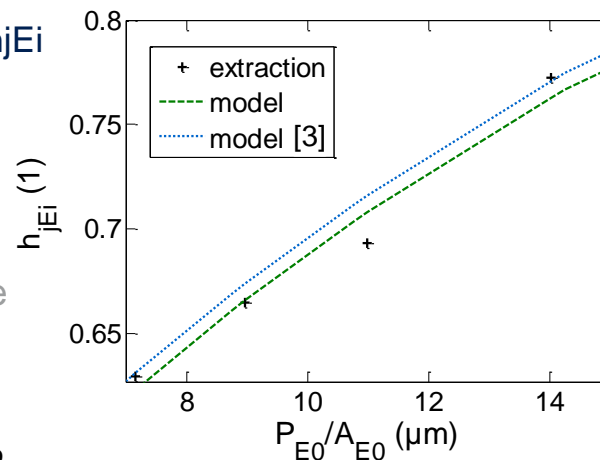
- Assume linear dependence for  $a_{hjEi}$

$$a_{hjEi} = a_{hjEi0} + a_{slope} \frac{P_{E0}}{A_{E0}}$$

- For  $P_{E0}/A_{E0} = 0$  the area value is obtained

- Verification

- Run simulations for all transistors considered in extraction
- Perform P/A separation on synthetic data
- Compare  $\gamma_C$

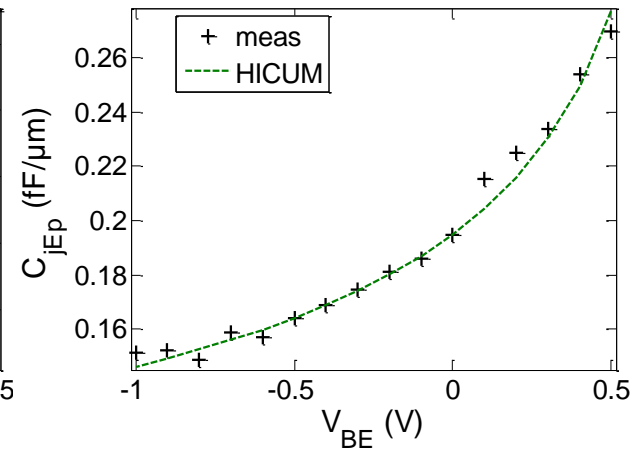
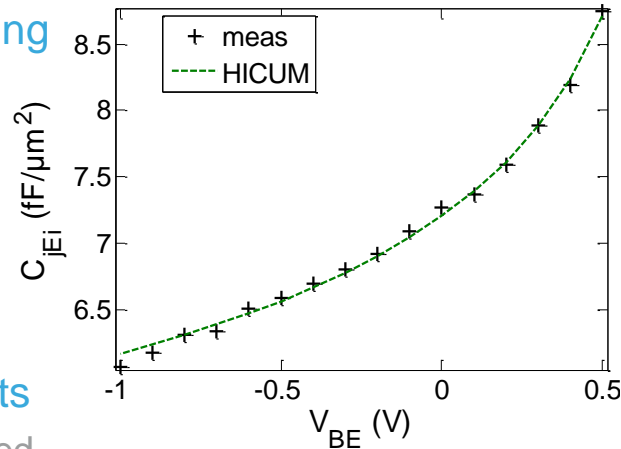


# Base emitter capacitance

- Perform standard P/A scaling

- Capacitance partitioning

$$C_{BE,meas} = C_{jEi}A_{E0} + C_{jEp}P_{E0} + C_{BEpar}P_{E0}$$



- Peripheral components

- Need to be distributed between junction- and spacer capacitance (bias independent)
    - Portions cannot be distinguished from geometry variation

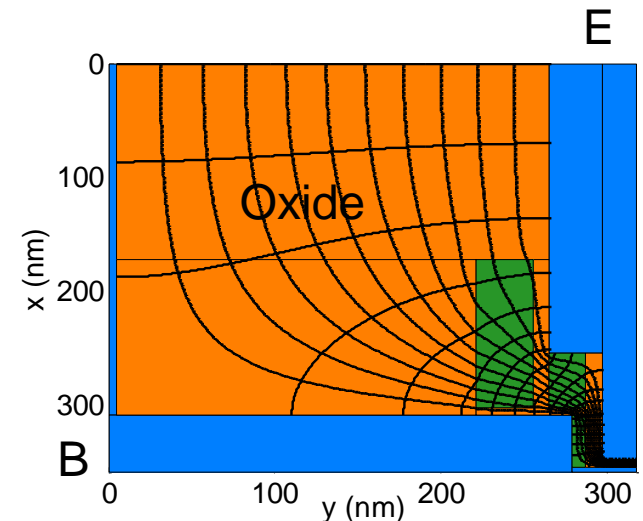
⇒ Perform EM simulation

- Field distribution of BE-spacer

- Geometry information can be obtained from SEM/TEM pictures

- Structure consists of Oxide, Nitride and (assumed) ideal contacts for Poly region

- $C_{BEpar} = 0.35 fF/\mu m$



- Scaling equation for low current transit time [6]

- Similar to description of  $h_{jEi}$
- Performs weighting between internal and peripheral transit time

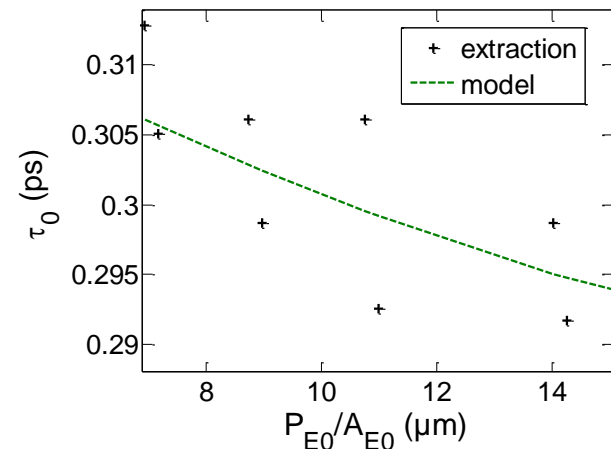
$$\tau_0 = \tau_{0a} \frac{1 + f_{t\pi i} \gamma_C \frac{P_{E0}}{A_{E0}}}{1 + \gamma_{C0} \frac{P_{E0}}{A_{E0}}} \quad f_{t\pi i} = \frac{\tau_{0p}}{\tau_{0a}}$$

- Various extraction methodologies

- Usually involve circuit simulation of different transistor sizes
  - Manual fine tuning of parameters
  - Global optimization on selected parameters
- Alternative
  - Use method of [5] for performing single transistor extraction and use obtained parameter values for scaling

- Result using method of [5]

- $\tau_{0a}$  and  $f_{t\pi i}$  are very sensitive to extracted values of  $\tau_0$
- Variability of  $\tau_0$  is very low (~7.5%)  
=> Extraction method must be accurate



[5] T. Rosenbaum et al. « Automated transit time and transfer current extraction for single transistor geometries ». Proc. IEEE BCTM, 2013.



# Internal collector resistance

- Modeling approach [6]

- $r_{Ci0}$  mainly depends on emitter area
- Current spreading
  - Is taken into account by current spreading factor

- Basic idea behind current spreading model

- Linear increase of current path envelope

$$A_C(x) = A_{E,eff} \left( 1 + 2 \tan(\delta_C) \frac{x}{b_E} \right)$$

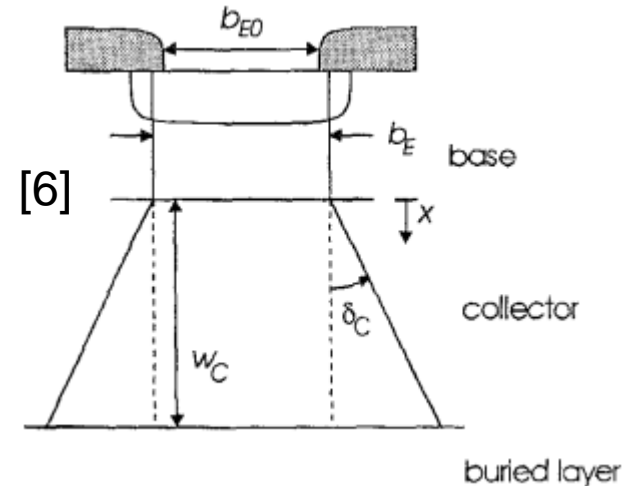
- Integration over  $1/A_C(x)$  leads to logarithm

$$r_{Ci0} = \frac{r_{Ci0a}}{f_{cs} A_E}$$

$$f_{cs} = \frac{LAT_b - LAT_l}{\ln[(1 + LAT_b)/(1 + LAT_l)]}$$

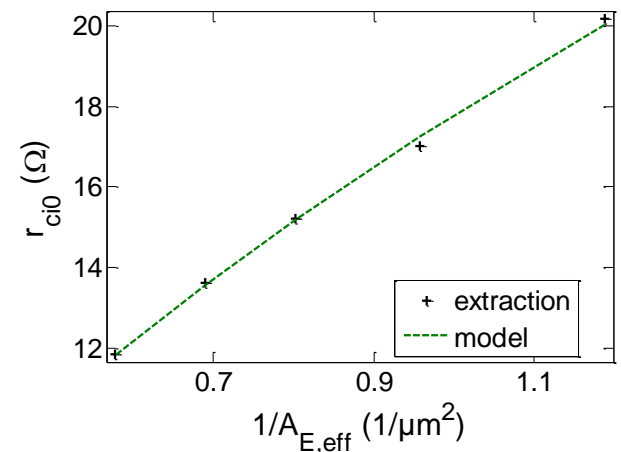
$$LAT_b = 2w_{Ci} \tan(\delta_C) / b_E$$

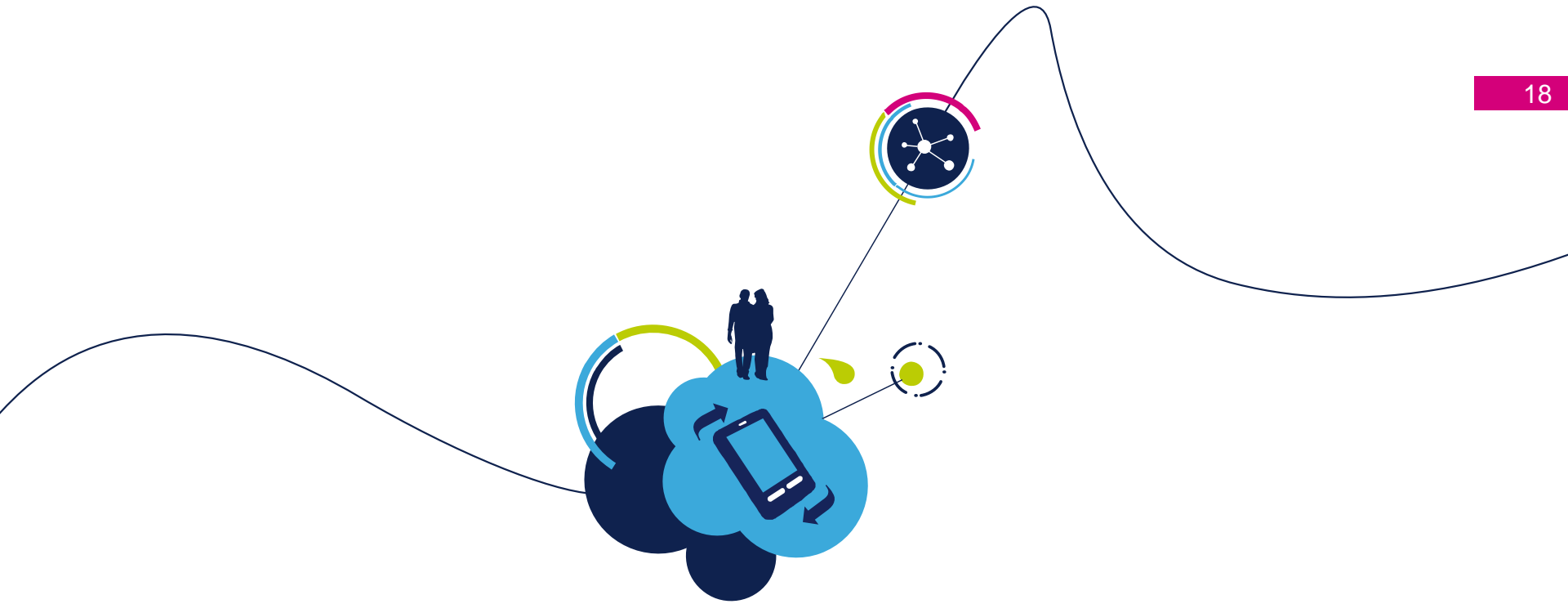
$$LAT_l = 2w_{Ci} \tan(\delta_C) / l_E$$



- Result

- Perform optimization for  $r_{Ci0a}$  &  $\delta_C$





# Results using scalable model (for selected transistors)

# Assessing extraction quality

- Collector current

- Allows to identify discrepancies at high current region
- Will not help to evaluate extraction for low currents

- Normalized collector current

- Is equal to 1 for low currents
- Allows to assess bias dependent  $h_{jEi}$

$$I_{C,norm} = \frac{I_C}{I_S \exp(V_{BEi}/V_T)} = \frac{1}{1 + h_{jEi} Q_{jEi}/Q_{p0}}$$

- Normalized transconductance

- Similar to  $I_{C,norm}$
- Useful to identify correct modeling of medium/high current fall-off

$$g_{m,norm} = \frac{g_m}{I_C} V_T$$

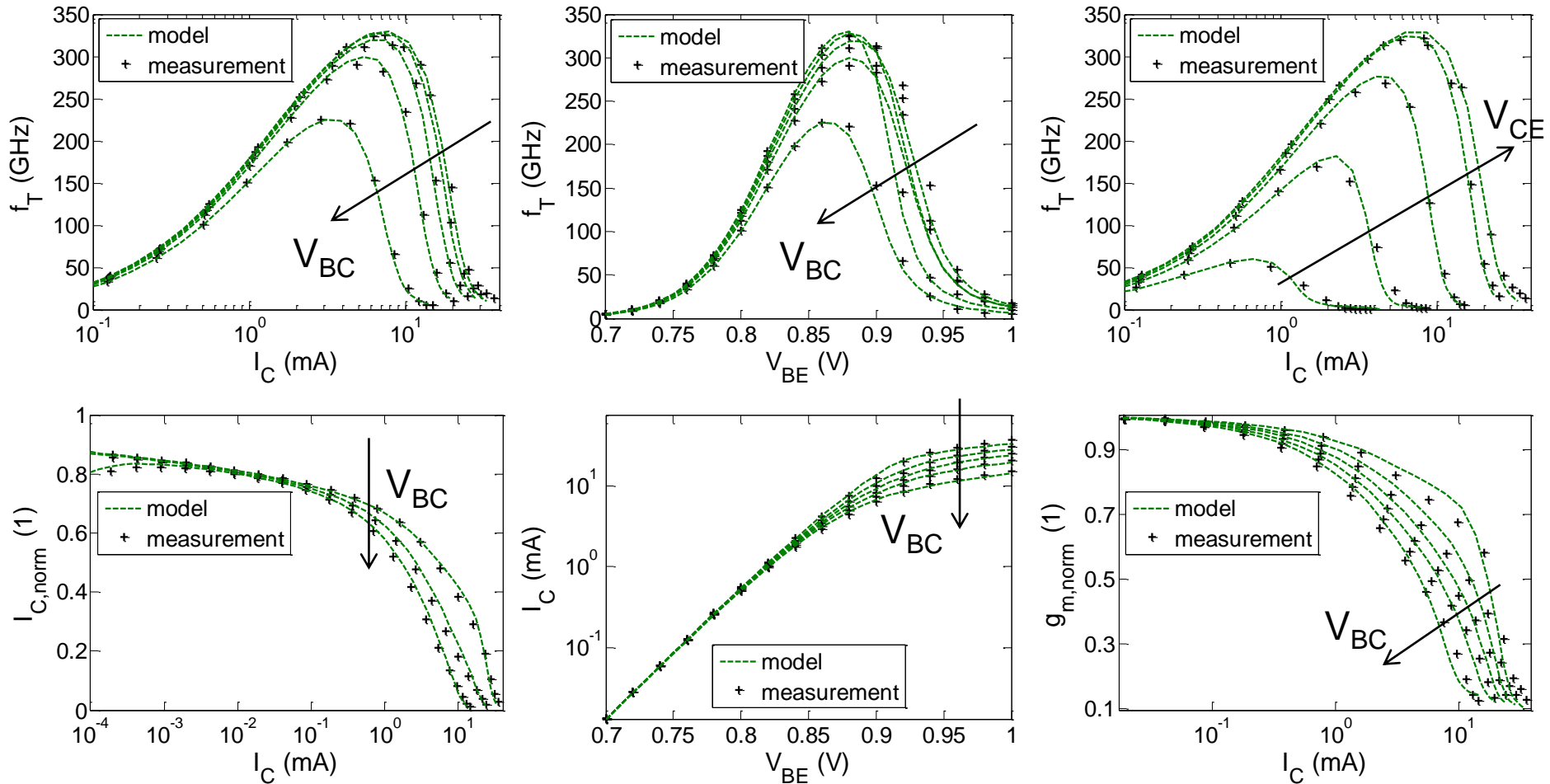
- Transit frequency

- Allows to assess correct transit time modeling
- Useful to include measurements at  $V_{CE} = \text{const}$ 
  - Shows model reliability in saturation

# Small high speed transistor

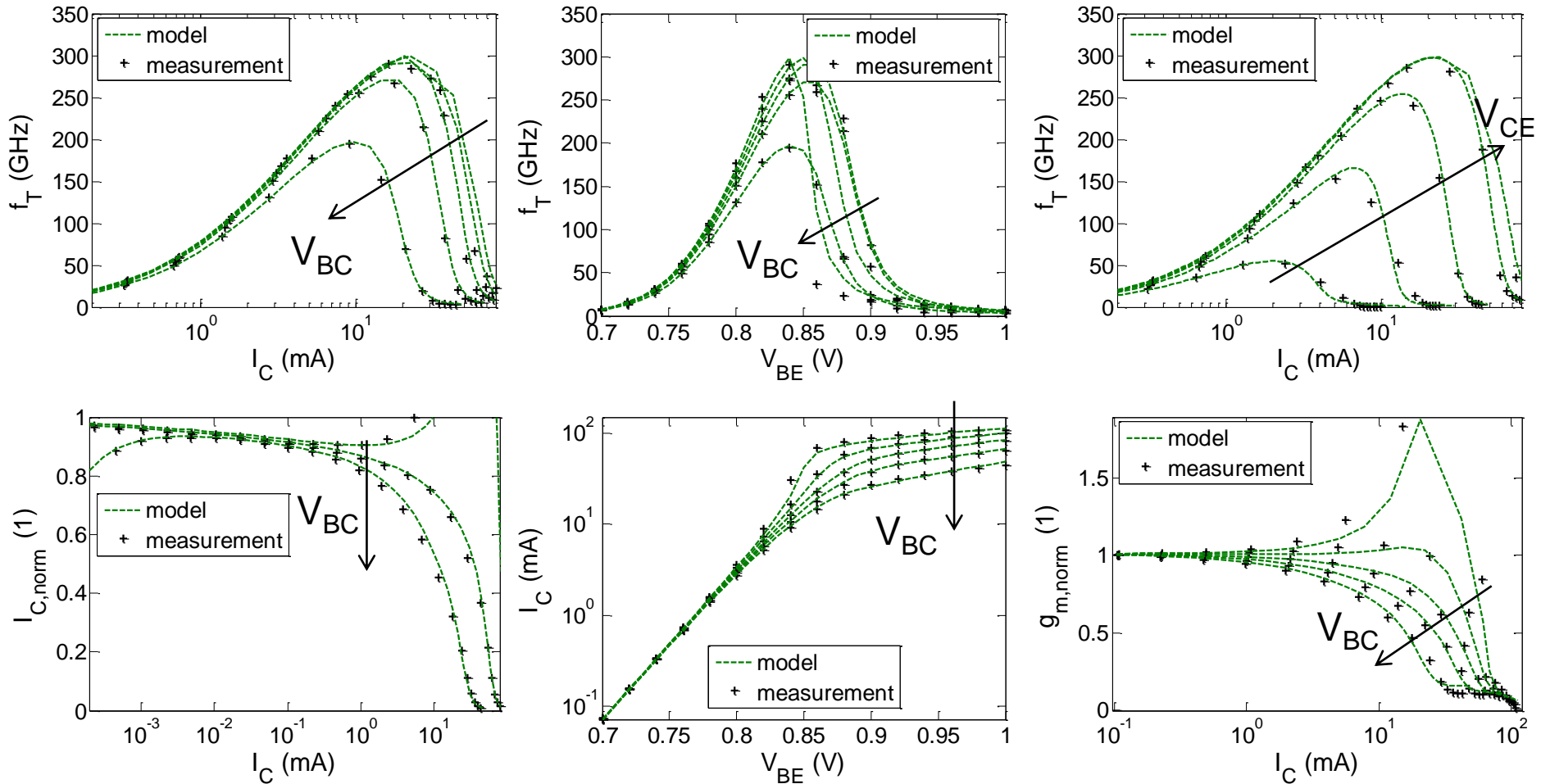
- $b_{E0} = 100 \text{ nm}$ ,  $l_{E0} = 4.42 \text{ } \mu\text{m}$

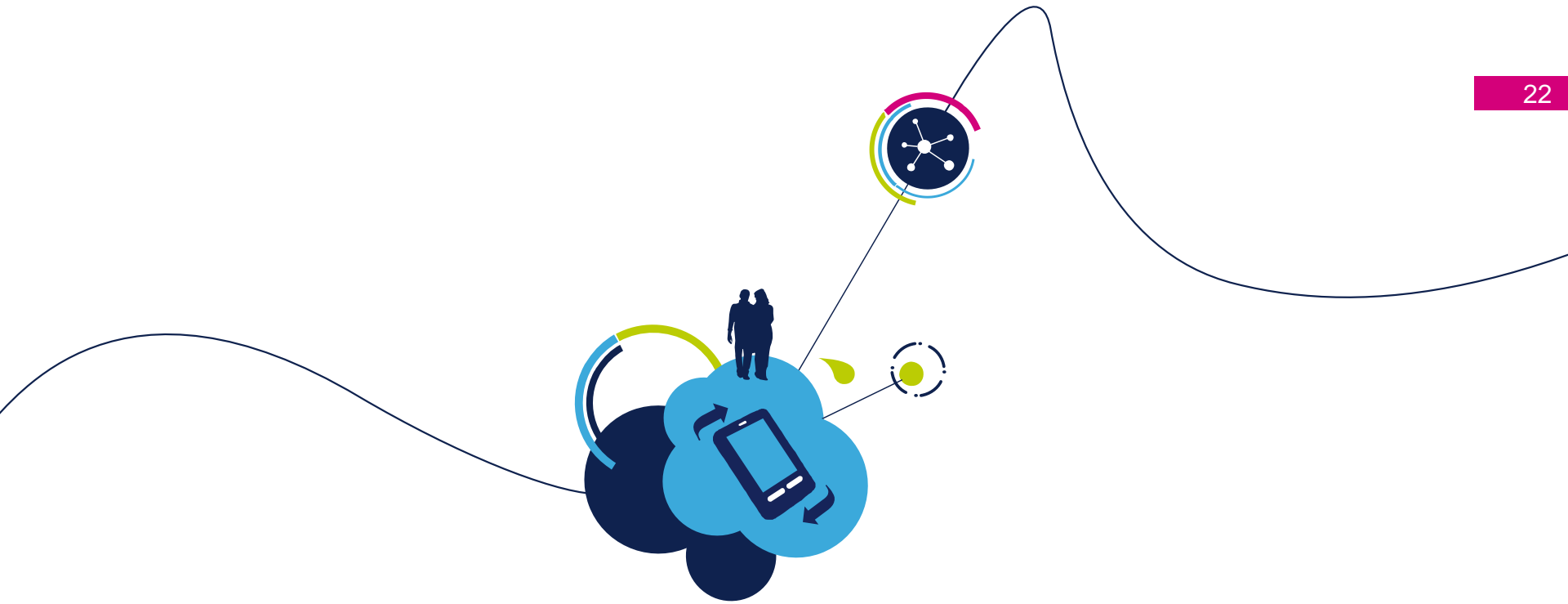
- $V_{BC} = [-0.5 \text{ } -0.25 \text{ } 0.0 \text{ } 0.25 \text{ } 0.5] \text{ V}$ ,  $V_{CE} = [0.1 \text{ } 0.25 \text{ } 0.5 \text{ } 1 \text{ } 1.5] \text{ V}$



# Large high speed transistor

- $b_{E0} = 300 \text{ nm}$ ,  $l_{E0} = 8.92 \text{ }\mu\text{m}$ 
  - $V_{BC} = [-0.5 \text{ } -0.25 \text{ } 0.0 \text{ } 0.25 \text{ } 0.5] \text{ V}$ ,  $V_{CE} = [0.1 \text{ } 0.25 \text{ } 0.5 \text{ } 1 \text{ } 1.5] \text{ V}$



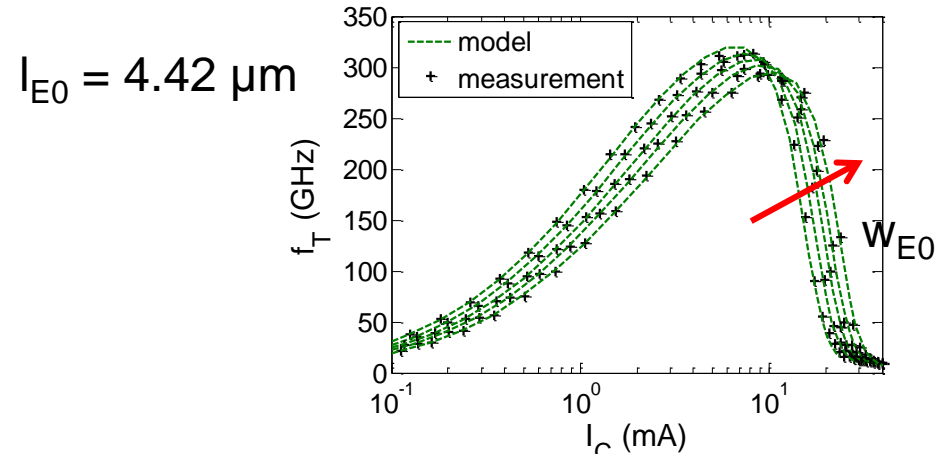


# Results overview for $V_{BC} = 0 \text{ V}$ (for all transistors)

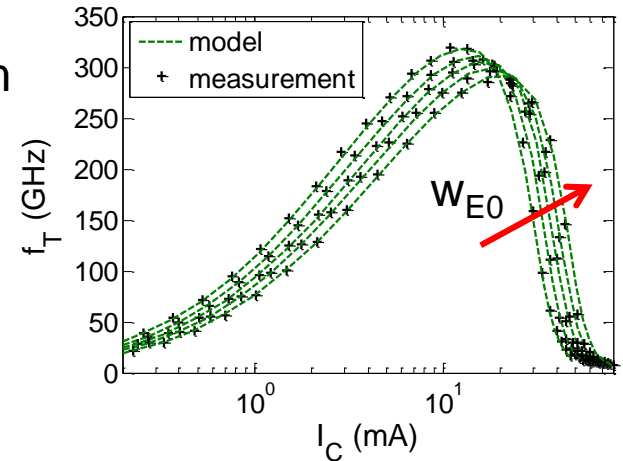
# Selected quantities at $V_{BC} = 0$ V

- Transit frequency ( $V_{BC} = 0$  V)

- $w_{E0} = [100 \ 145 \ 190 \ 235 \ 300]$  nm

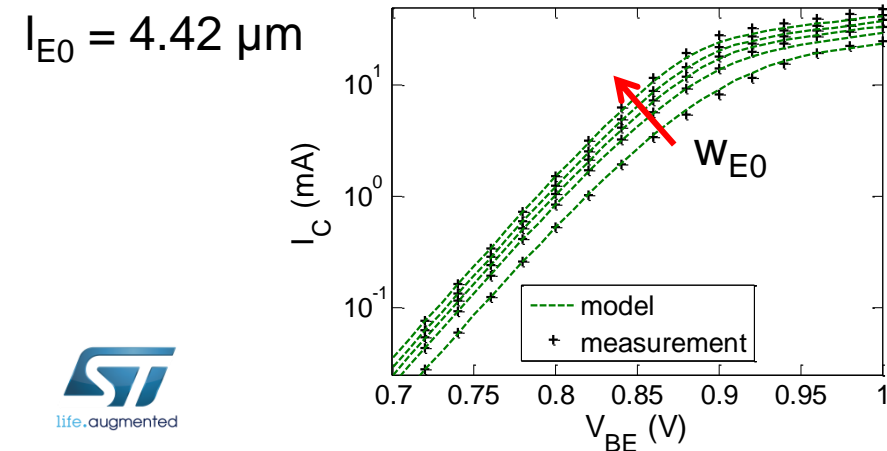


$I_{E0} = 8.92 \mu\text{m}$

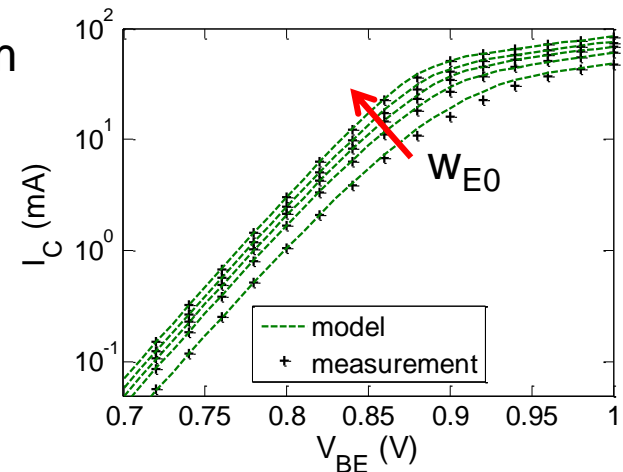


- Collector current ( $V_{BC} = 0$  V)

- $w_{E0} = [100 \ 145 \ 190 \ 235 \ 300]$  nm



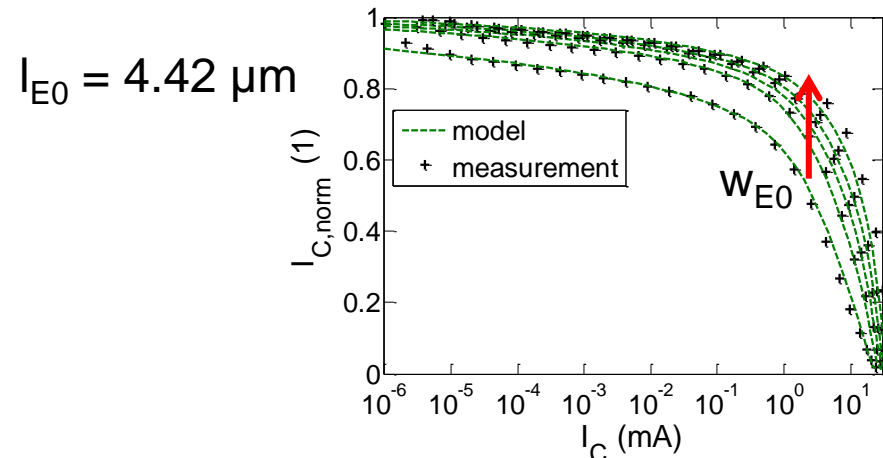
$I_{E0} = 8.92 \mu\text{m}$



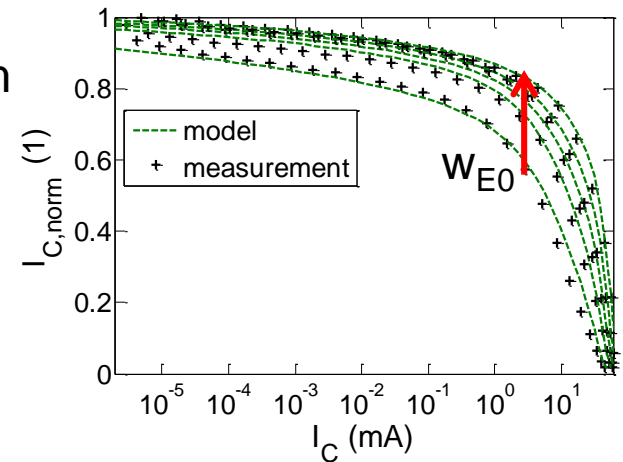
# Selected quantities at $V_{BC} = 0$ V

- Normalized collector current ( $V_{BC} = 0$  V)

- $w_{E0} = [100 \ 145 \ 190 \ 235 \ 300]$  nm

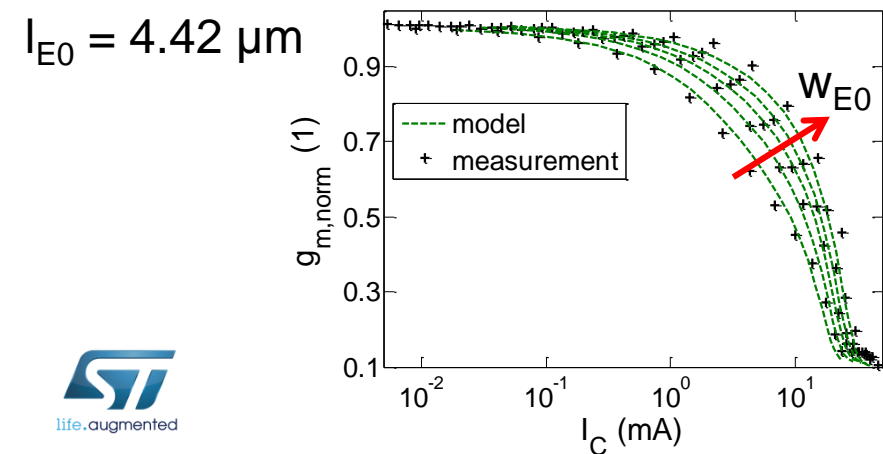


$I_{E0} = 8.92 \mu\text{m}$

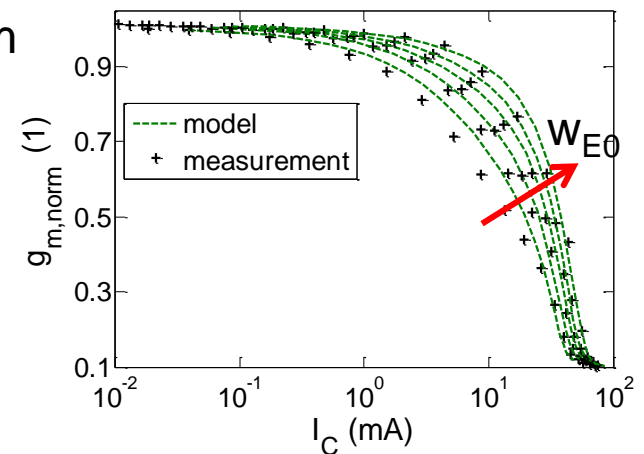


- Normalized transconductance ( $V_{BC} = 0$  V)

- $w_{E0} = [100 \ 145 \ 190 \ 235 \ 300]$  nm



$I_{E0} = 8.92 \mu\text{m}$





- Introduction on geometry scaling for HBTs
  - Standard scaling approach (P/A)
    - Remains sufficient for Capacitance modeling
  - Transfer current scaling –  $\gamma_C$  approach
    - Is not suitable anymore for advanced HBTs
    - Voltage dependence of area and perimeter differ too much
  - Enhanced transfer current scaling
    - Enables to model the bias dependence of  $\gamma_C(V_{BE})$  by modulating the weight factor  $h_{jEi}$
    - Result can be enhanced by adding a linear geometry dependence for  $a_{hjEi}$
- Example extraction for an advanced SiGe technology [2]
  - Shows excellent agreement for both bias and geometry dependence
    - Bias dependent  $\gamma_C$  can be observed for normalized transfer current
    - Model features single geometry scalable modelcard for all transistors
  - Important cornerstones for geometry dependence of  $f_T$ 
    - Proper geometry modeling of the low current transit time and internal collector resistance

[2] P. Chevalier et al. « A 55 nm Triple Gate Oxide 9 Metal Layers SiGe BiCMOS Technology Featuring 320 GHz  $f_T$  / 370 GHz  $f_{MAX}$  HBT and High-Q Millimeter-Wave Passives ». Proc. IEEE IEDM, 2014.

Thank you for your attention!

- [1] M. Schroter, A Chakravorty. «Compact hierarchical bipolar transistor modeling with HICUM». World Scientific, 2010.
- [2] P. Chevalier et al. « A 55 nm Triple Gate Oxide 9 Metal Layers SiGe BiCMOS Technology Featuring 320 GHz fT / 370 GHz fMAX HBT and High-Q Millimeter-Wave Passives ». Proc. IEEE IEDM, 2014.
- [3] A. Pawlak et al. « Geometry scalable model parameter extraction for mm-wave SiGe-heterojunction transistors ». Proc. IEEE BCTM, 2013.
- [4] G. Wedel. « POICAPS - A multidimensional numerical capacitance simulator ». CEDIC internal document, 2012.
- [5] T. Rosenbaum et al. « Automated transit time and transfer current extraction for single transistor geometries ». Proc. IEEE BCTM, 2013.
- [6] M. Schroter et al. « Physical modeling of lateral scaling in bipolar transistors ». IEEE Journal of Solid-State Circuits, 1996.

- Bias dependence of  $h_{jEi}$

$$h_{jEi} = h_{jEi0} \frac{\exp(u) - 1}{u}$$

$$u = a_{h_{jEi}} \left( 1 - \left[ 1 - \frac{v_j}{V_{DEi}} \right]^{z_{Ei}} \right)$$

- $V_j$  is the smoothed Base emitter voltage  $V_{BEi}$ 
  - Range:  $0 < V_j < V_{DEi}$